

MicroThin™ Series



MicroThin™

帶載體的超薄銅箔

Ultra Thin copper foil with removable Carrier



三井金屬

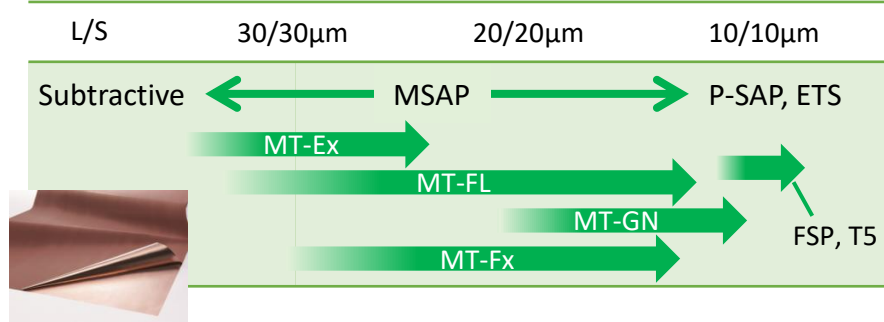
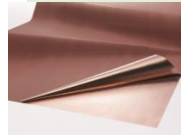
最適用於MSAP L/S $\leq 30/30\mu\text{m}$ 微細線路製程。

Usable for very fine pitch pattern under L/S $\leq 30/30\mu\text{m}$ formation.

MicroThin™ Structure



Target L/S with MicroThin™



		MT18(12)Ex	MT18(12)FL	MT12(18)GN	MT18Fx	FSP501	MT18SD-H-T5
Structure							
Nominal Thickness [μm]		2 / 3 / 5	1.5 / 2 / 3	1.5 / 2 / 3	1.5 / 2 / 3	1.5	5
Roughness [μm]	Rz	2.0	1.3	0.9	1.4	1.4	1.0
	Ra	0.3	0.2	0.15	0.2	0.2	0.12
Lamination side SEM							

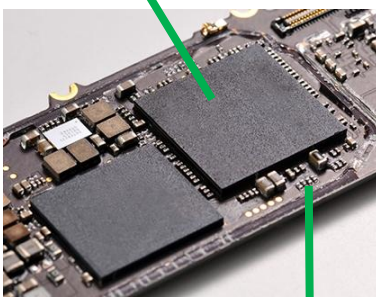
上述數據僅供參考，不作為保證。These are representative data and are not guaranteed.

主要PCB應用領域

Major PCB applications

Package

FC-CSP, BOC, Module substrate etc.



HDI SLP(Substrate Like PCB)

主要終端應用領域

Major end applications

Mobile Devices

SoC, RF module, AiP, LPDDR/UFS, Mainboard etc.



AI server

DDR, LPDDR, GDDR, NAND(SSD), Optical Transceiver etc.



本資訊截至2026年9月9日內容如有變更恕不另行通知

This information is as of Sep. 9th, 2026, and subject to change without notice.